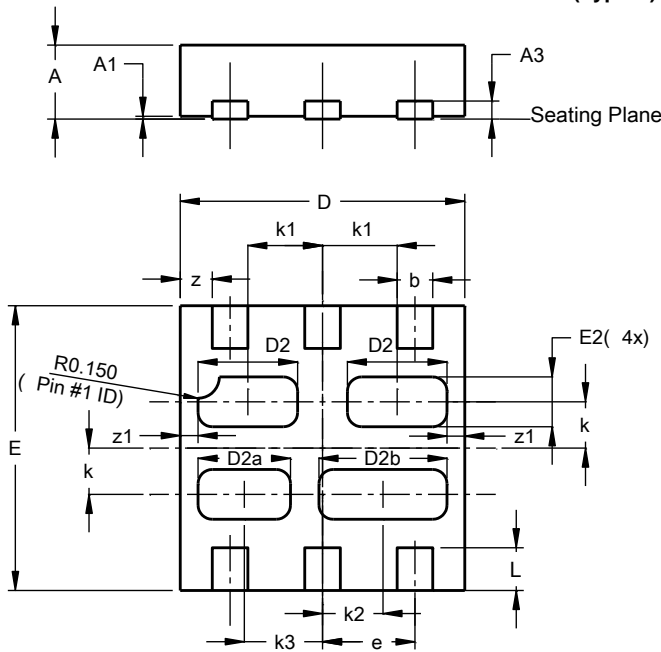


Package Outline Dimensions

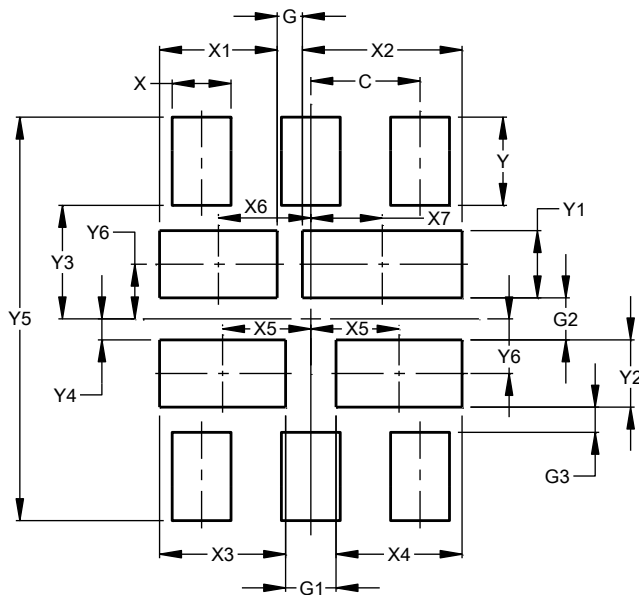
U-DFN2020-6 (Type P)



U-DFN2020-6 (Type P)			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0.00	0.05	0.02
A3	--	--	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
D2	0.60	0.80	0.70
D2a	0.55	0.75	0.65
D2b	0.80	1.00	0.90
E	1.95	2.075	2.00
E2	0.25	0.45	0.35
e	0.65 BSC		
L	0.25	0.35	0.30
k	--	--	0.325
k1	--	--	0.525
k2	--	--	0.425
k3	--	--	0.550
z	--	--	0.225
z1	--	--	0.125
All Dimensions in mm			

Suggested Pad Layout

U-DFN2020-6 (Type P)



Dimensions	Value (in mm)
C	0.650
G	0.150
G1	0.300
G2	0.250
G3	0.150
X	0.350
X1	0.700
X2	0.950
X3	0.750
X4	0.750
X5	0.525
X6	0.550
X7	0.425
Y	0.525
Y1	0.400
Y2	0.400
Y3	0.675
Y4	0.125
Y5	2.400
Y6	0.325

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.